

TFC*1 Embedded Substrate "GigaModule-EC"

New proposal for high performance and energy-saving semiconductor

Note*1: Thin Film Capacitor

GigaModule-EC, a best suitable substrate for next high-performance & energy-saving semiconductor

To make high performance and energy-saving semiconductor devices work stably, power management becomes very important. A decoupling capacitor with large capacity and low power impedance, at ultra-high frequency, is strongly needed for the power stabilization. "GigaModule-EC" enables TFC embedded semiconductor substrates with low inductance and effective use of space for wiring patterns and device mounting.

■ Effective improvements at high frequency

 TFC is aimed to be embedded just under the die in a semiconductor packaging substrate, enabling low V/G impedance at high frequency by connecting via VIAs.

Electric capacitance is designed as needed

- The electric capacity can be set as designed with TFC area, formed with the etching process.
- 2 types of TFC materials are available:
 Normal Capacity type: 1.0μF/cm²
 Large Capacity type: 2.0μF/cm²

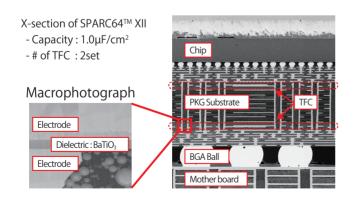
■ Effective use of device mounting spaces

 Embedded TFC enables the reduction of surface mount chip capacitors. Also, its narrow pitch Via connection expands its wiring capacity.

Practical use of TFC

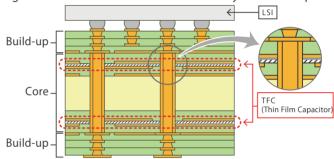
Fujitsu Limited SPARC64 processor SPARC64™ XII

- Max Freq. : 4.25GHz- # of CPU core : 12 cores- I/O band width : 64GB/s

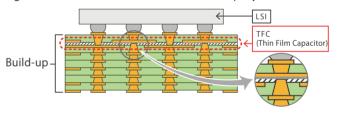


Advantage : Structural type selection

GigaModule-2EC: TFC embedded in core layer of build-up PCB

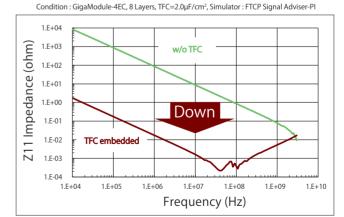


GigaModule-4EC: TFC embedded in build-up layer of coreless PCB



Advantage: Electrical characteristics

Embedded TFC makes V/G impedance reduce effectively



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